

ABSTRACT OF THE DISCLOSURE

[032] A bond out chip 60 for use with an in-circuit emulator. The bond out chip 60 is formed by use of a first chip 10a and an adjacent chip 10b. Chips 10a and 10b have architectures substantially identical to the standard production chips that chip 60 is used to analyze or emulate. The first chip 10a is formed with an active core portion 12a, while the production chip 10b is formed with a disabled core portion 12b. The core portion 12a of chip 10a is connected to the input/output buffers and pads 18b, 20b of the adjacent chip 10b, thereby forming bond out chip 60.

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